

# State-of-the-Art and Challenges of Pressure-Tolerant Power Electronics and a Review of Related Research at NCSU

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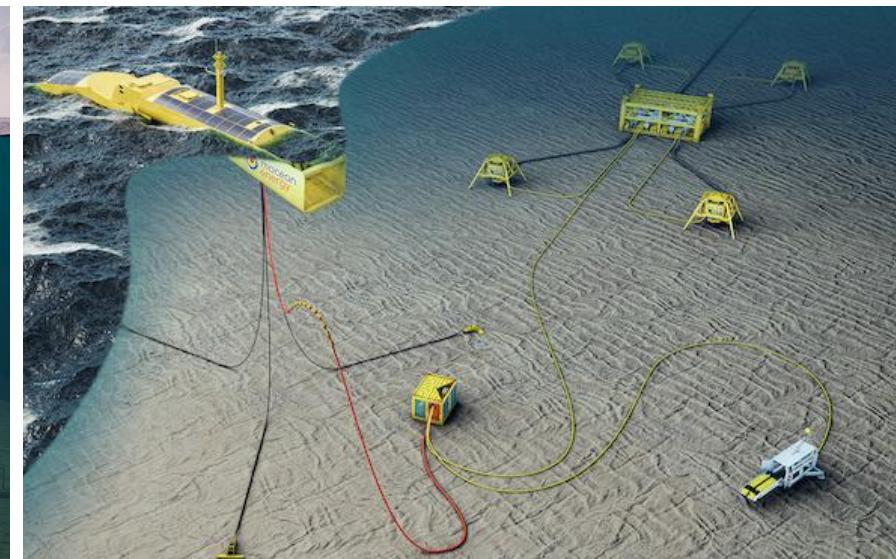
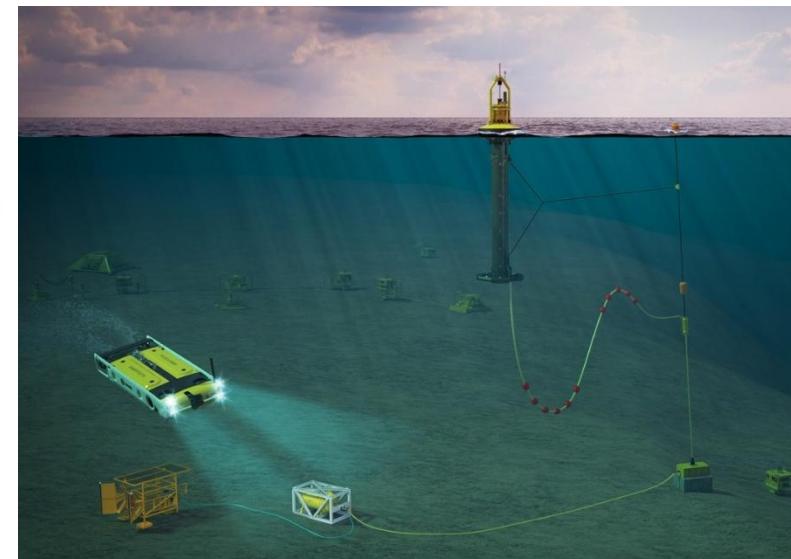
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*August 13, 2025*

- Motivation
- State of the art of pressure tolerant power electronics (PTPE)
- Developmental challenges of PTPE for subsea application
- Research on PTPE at NCSU

- Sustainable microgrid is required for offshore marine energy generation and loads
- Power umbilical is not suitable for deep offshore applications
- Offshore power converters are required for power regulations



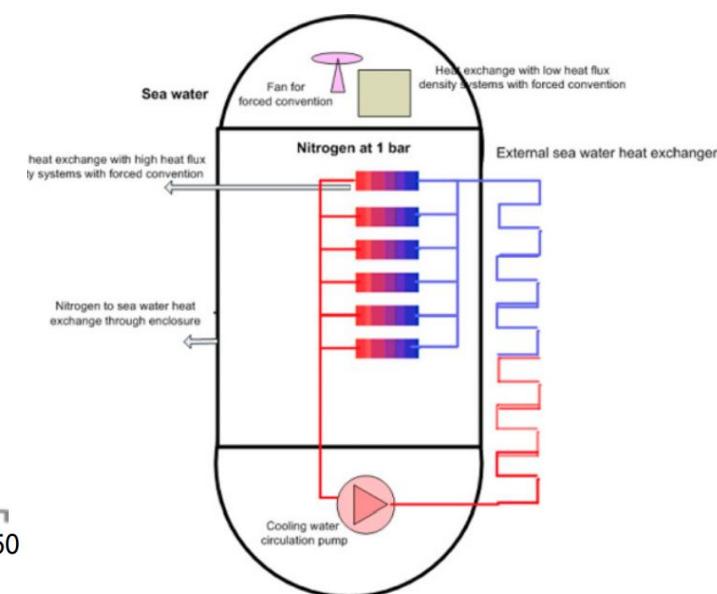
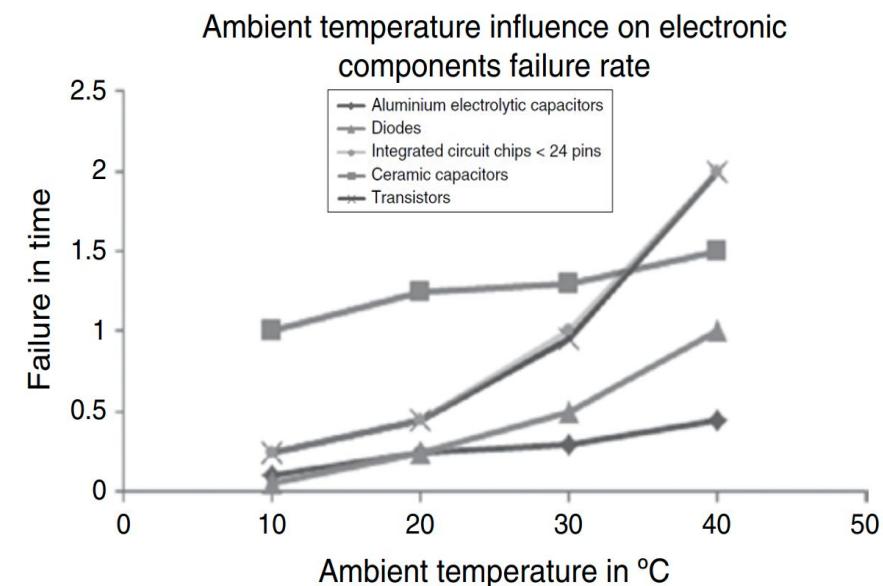
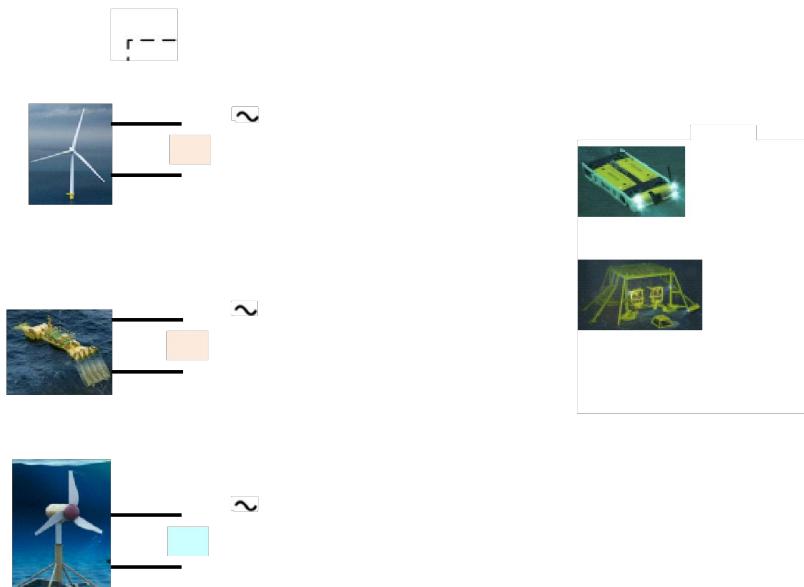
Artistic view of marine energy generation for a subsea power system <sup>(1)</sup>

Integrated subsea loads for marine exploration, monitoring, and surveillance <sup>(2)</sup>

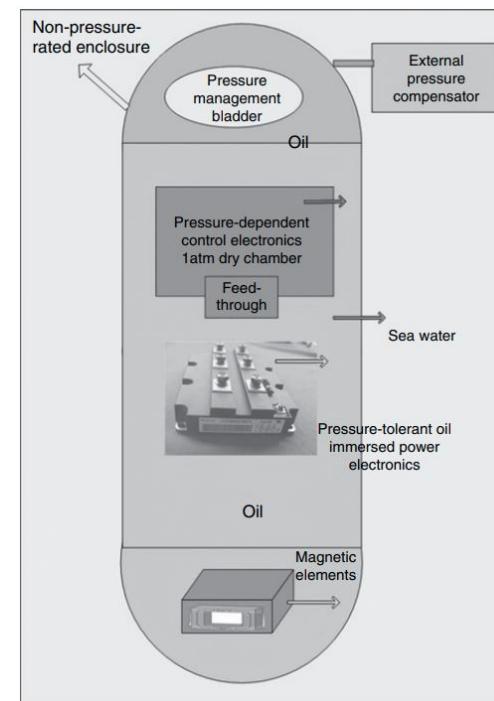
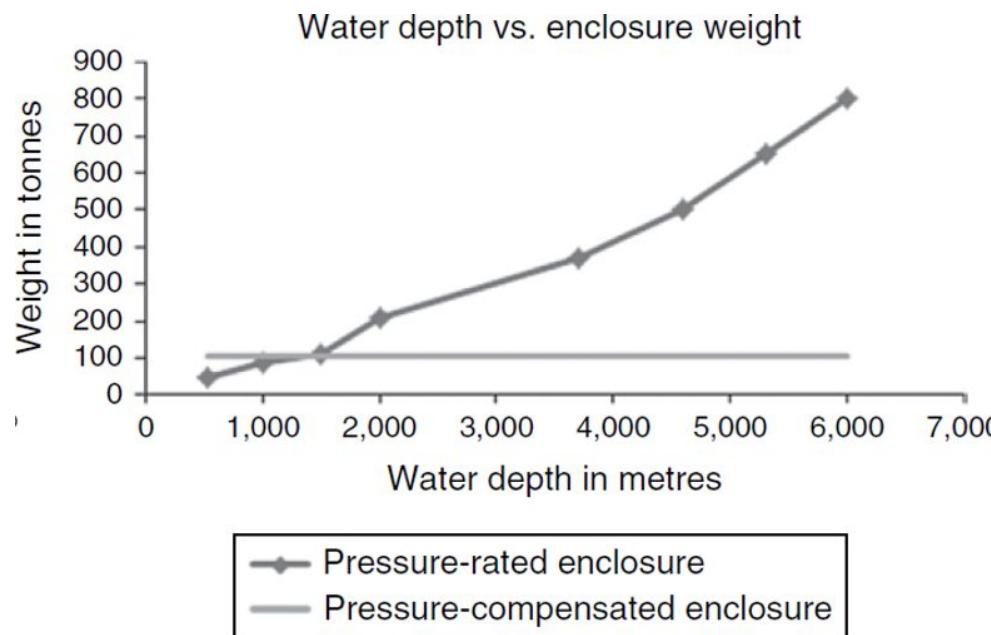
An offshore islanded microgrid <sup>(3)</sup>

1. <https://www.offshore-mag.com>  
2. <https://www.offshorewind.biz/>  
3. <https://waves-energy.co/blog/>

- Power converter becomes a building block of the microgrid
- Failure rate of electronic components increases based on the ambient temperature
- **Incorporation of thick metallic cylinders requires a sophisticated heat exchange mechanism**

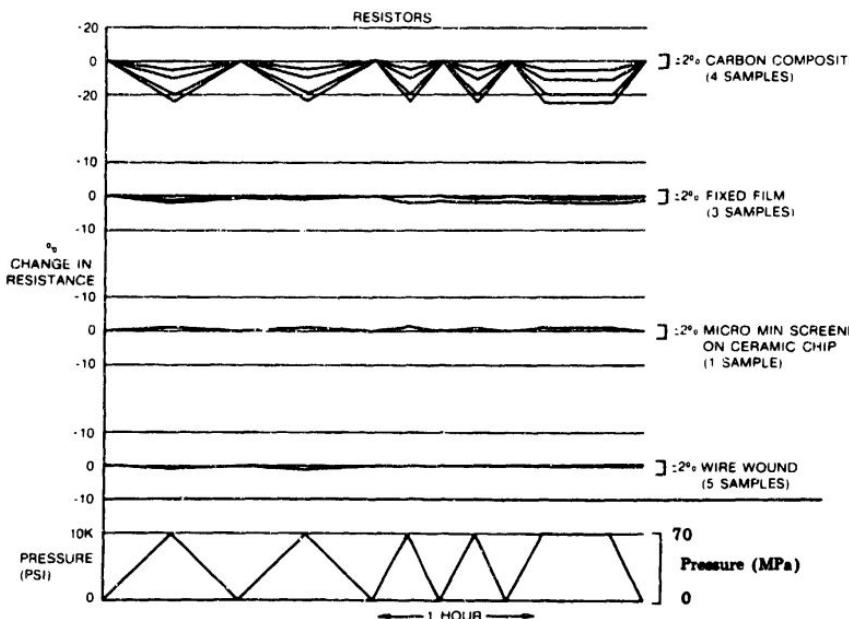


- Significant weight of cylinder is added at higher water depths
- Pressure-compensated enclosure is independent of water depth

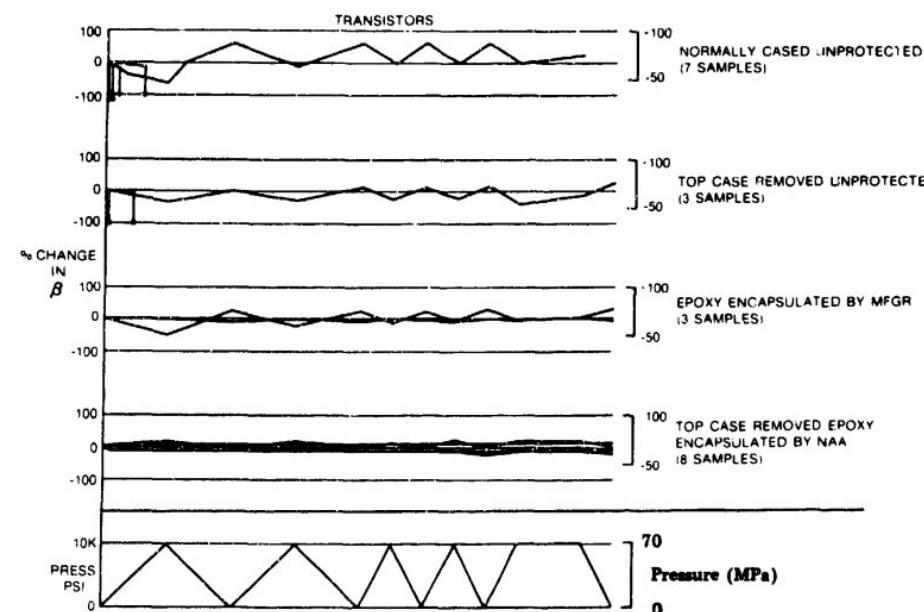


**We need pressure-tolerant power electronics (PTPE)!!!!!!**

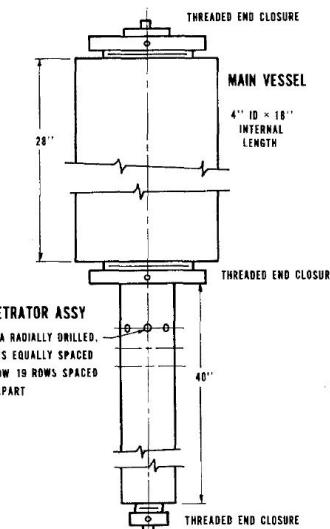
- First wave of PTPE research in the 1970s by Barnes and Gennari
  - Outdated technological components
  - Lack of live pressure testing



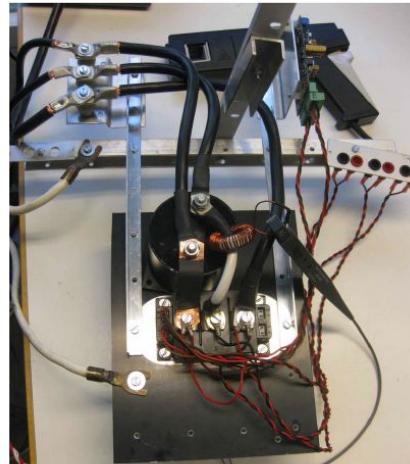
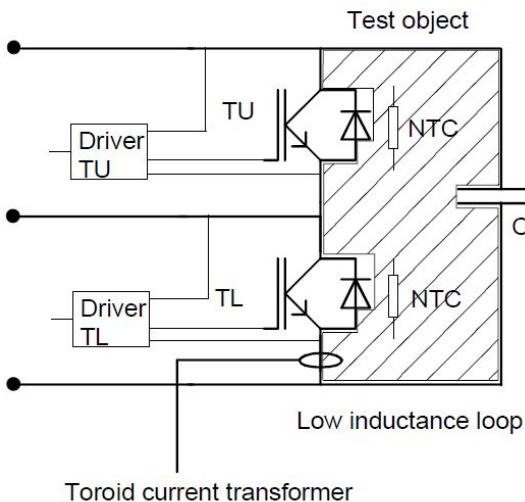
Results of resistor tests



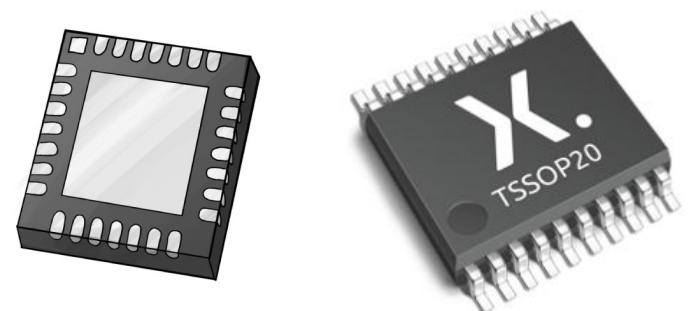
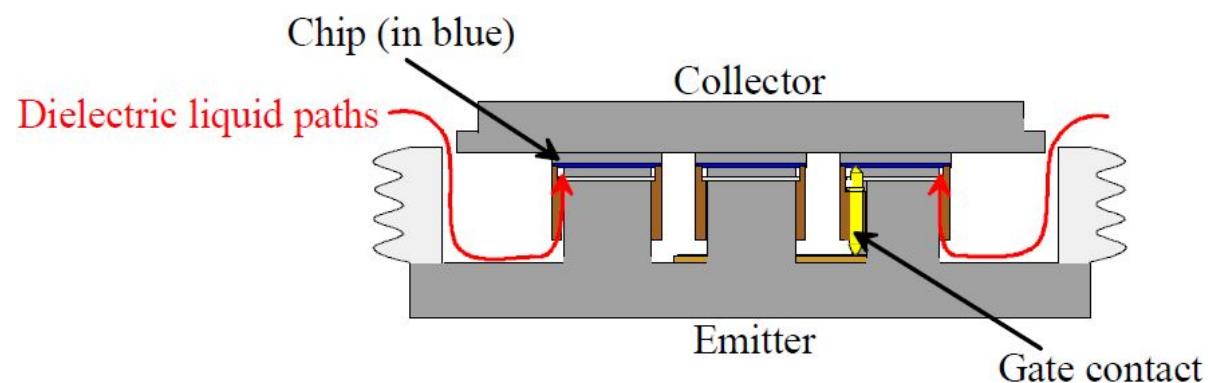
Results of transistor test



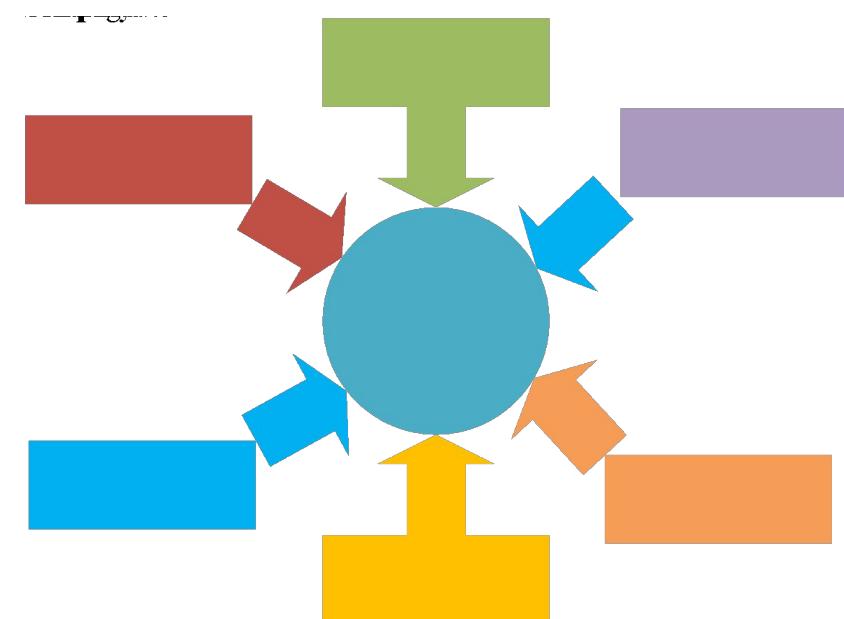
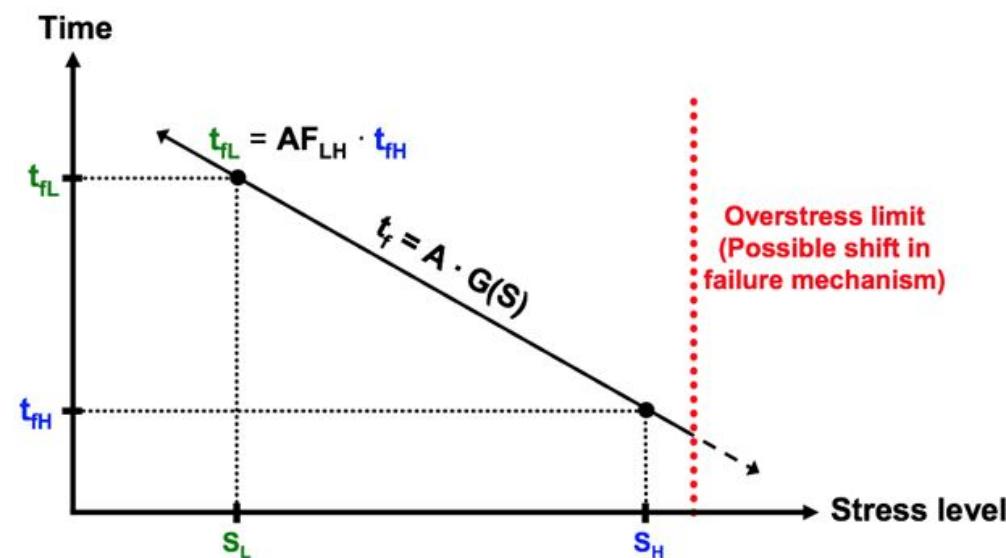
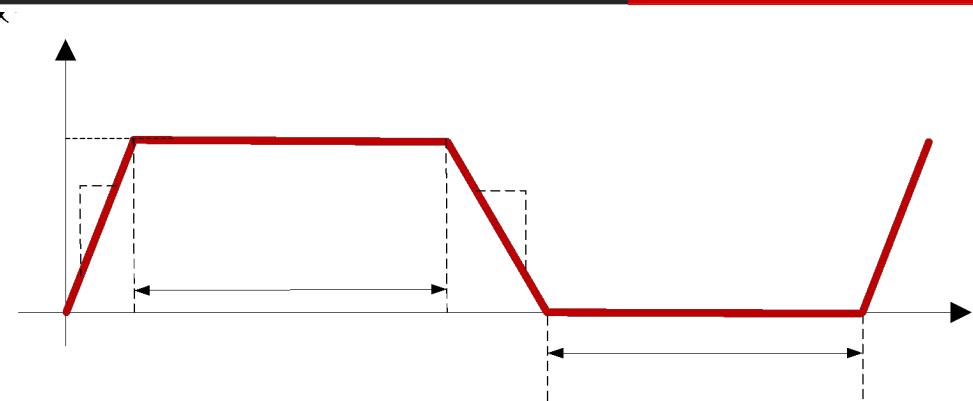
- Second wave of PTPE research in the 2000s by Hernes and Pittini for offshore oil and gas exploration.
  - Identified the bus capacitor, switching component, and gate driver as the central part of the converter
  - Off-the-shelf packaged switching components failed at high pressure due to voids



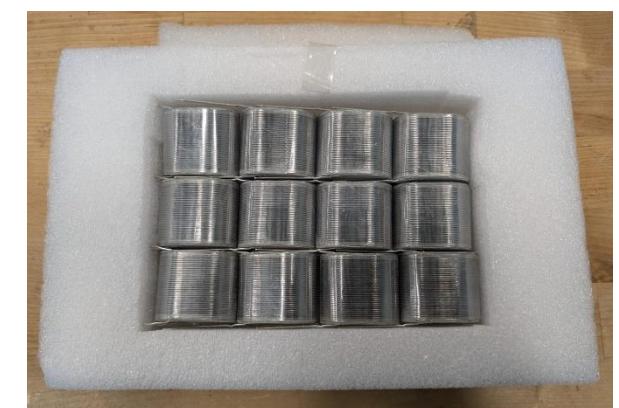
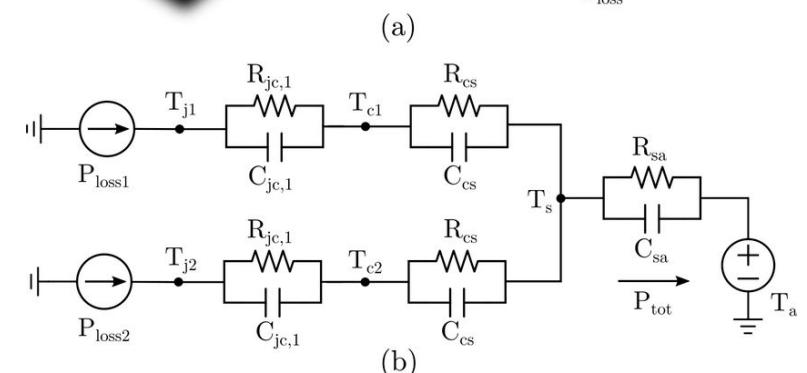
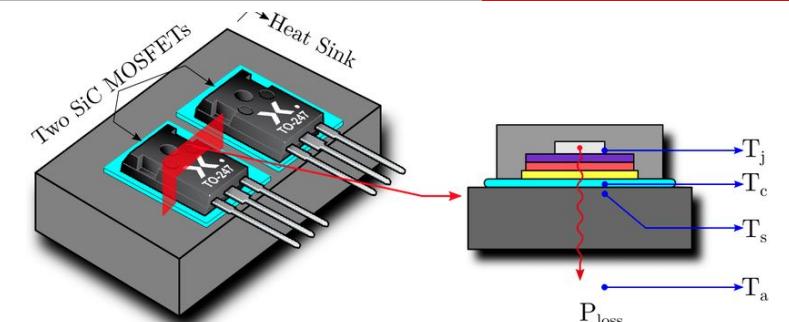
- Third wave of Modification of electronic components allows a void-less configuration and improves mechanical and structural performance
  - Tightly packed electronic components with leaded packaging offer extra room for pressure compliance



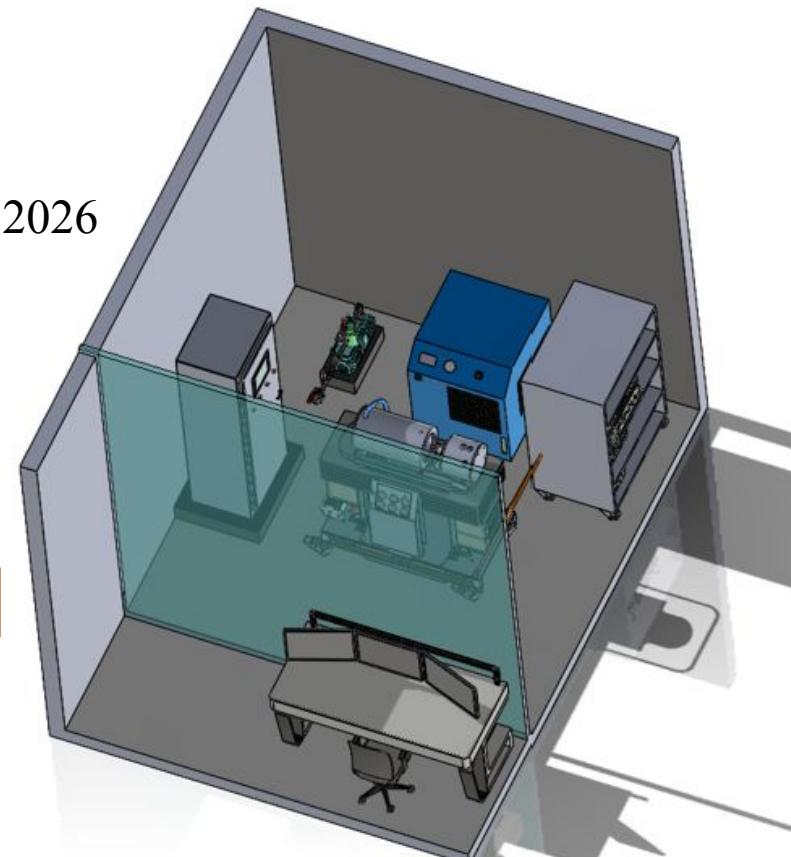
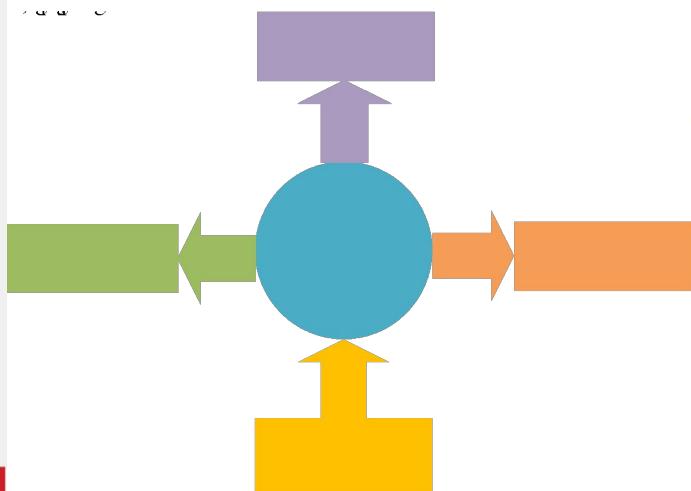
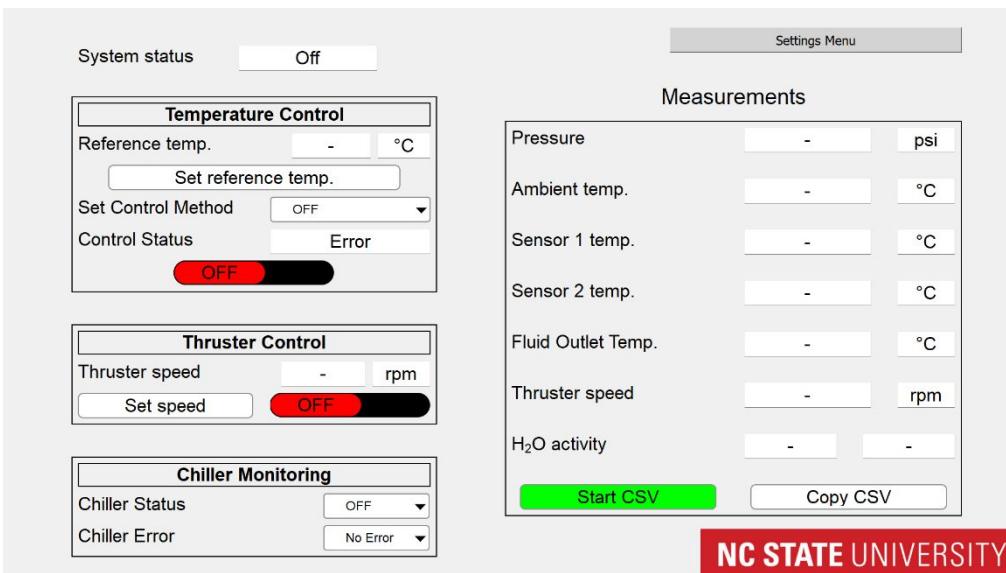
- Lack of unified testing methodology
  - Pressure profiles
  - Multi-Stressor Integration
  - Component level and system level alignment
  - Long-term impacts testing
    - Lack of accelerated life test (ALT) models based on pressure



- Lack of pressure-related component models
  - Component pressure model
  - Sample sizing
  - Subsea temperature environment
- Modeling and simulation gap
  - Co-simulation of pressure-thermal-electrical simulation
- Device packaging and design
  - Voidless design challenge
  - Thermal management challenges
  - Insulation and dielectric strength challenges

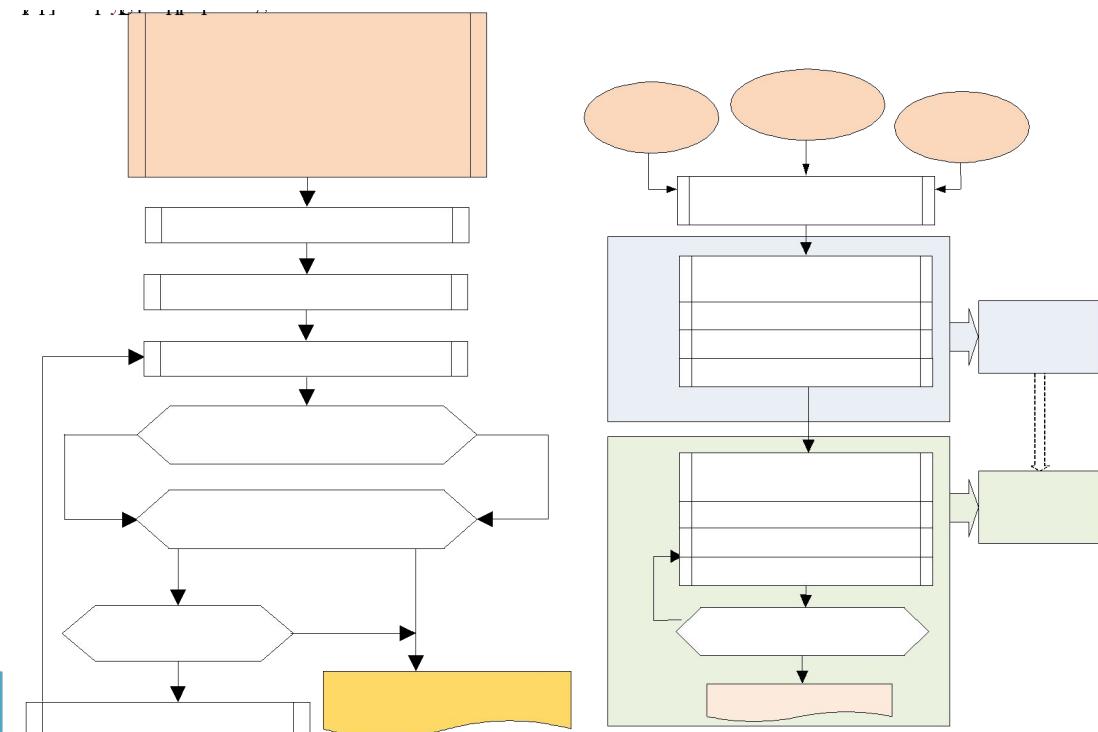
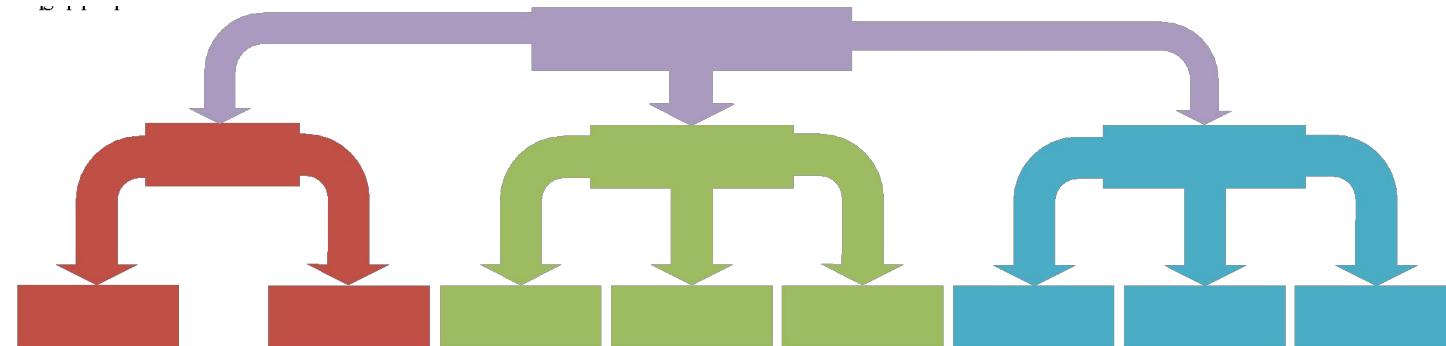


- NSF funded project – develop an automated test station for pressure tolerant electronics
  - Development of live pressure testing capability
  - Remote and autonomous operation in a fully-controllable environment
  - Pressure range:  $1.4 \times 10^{-3}$  to 10,000 psi
  - Ambient temperature range: -10°C to +40°C
  - Voltage and current range: 3 kV, 30 A
  - The station will be ready for energized pressure testing by the end of 2025/early 2026



## □ Power electronic device characterization

- Benchmark testing
- Passive pressure testing
- Live pressure testing



But it is a long way to go!!!!!!

